**PCN 18\_0064**

**PCN Title: Bump Site Transfer and Qualification of Select 6L and 8L SOT23 Flip Chip on Lead Packages**

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| **Change Items** | **From** | **To** |
| Bumping Site | Amkor Taiwan (AT5) | Chipbond, Taiwan (CB4) |
| Die Level Bumping | High Lead Bumping | Cu Pillar/SnAg Bumping |
| Assembly | High Lead bumped die Flip Chip on Lead assembly with Solder Screen Printing on leadframe step before Flip Chip attachment on leadframe | Cu Pillar/SnAg bumped die Flip Chip on Lead assembly process where the Solder Screen Printing on leadframe step is replaced with Flux Dip step before Flip Chip attachment on the leadframe |